



News Release

Unisem Recorded Revenue of RM990.6 million (approximately US\$315.3 million) for 2013

Kuala Lumpur, 26 February 2014 – Unisem (M) Berhad today announced results for the fourth quarter ended 31 December 2013 (**4Q13**).

Unisem recorded a consolidated revenue of RM247.1 million (approx. US\$77.0 million) for 4Q13, which represents 0.1 percent increase from the preceding quarter (**3Q13**) and decline of 8.3 percent compared to revenue recorded in the same quarter a year ago (**4Q12**). Despite lower revenue, gross profit margin for 2013 improved to 6.4 percent from 5.7 percent.

The Group recorded a consolidated net loss of RM93.1 million (approx. US\$29.0 million) for 4Q13 compared to net loss of RM1.1 million (approx. US\$344,000) in 3Q13 and net loss of RM20.2 million (approx. US\$6.59 million) in 4Q12. The consolidated net loss for the quarter was mainly attributable to impairment losses on goodwill and assets, provision for write-off on inventory and retrenchment costs.

Group earnings before interest, tax, depreciation and amortization (**EBITDA**) for 4Q13 came in at about RM36.4 million (approx. US\$11.4 million), EBITDA margin was about 15 percent. Equipment capacity utilization averaged at about 60 percent for the Group in 4Q13. Group capital expenditure incurred in 4Q13 was about RM5.3 million (approx. US\$1.6 million), principally for purchase of equipment for advanced packaging activities for Unisem (M) Berhad and Unisem Chengdu.

Commenting on the outlook of the Group, Mr. John Chia Sin Tet, group managing director said, "The operating environment continues to be challenging due to global economic uncertainties. However, the directors expect the performance of the Group in financial year 2014 to show an improvement as compared to that of the preceding year due to the Group's on-going efforts to contain costs and re-align its business model as well as the anticipated recovery in the semiconductor industry."

About Unisem

Unisem is a global provider of semiconductor assembly and test services for many of the world's most successful electronics companies. Unisem offers an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding, a wide range of leadframe and substrate IC packaging, wafer level CSP and RF, analog, digital and mixed-signal test services. Our turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. With approximately 6800 employees worldwide, Unisem has factory locations in Ipoh, Malaysia; Chengdu, People's Republic of China; Batam, Indonesia and Sunnyvale, USA. The company is headquartered in Kuala Lumpur, Malaysia. For more information about the company, its products and services, please visit its website at www.unisemgroup.com.